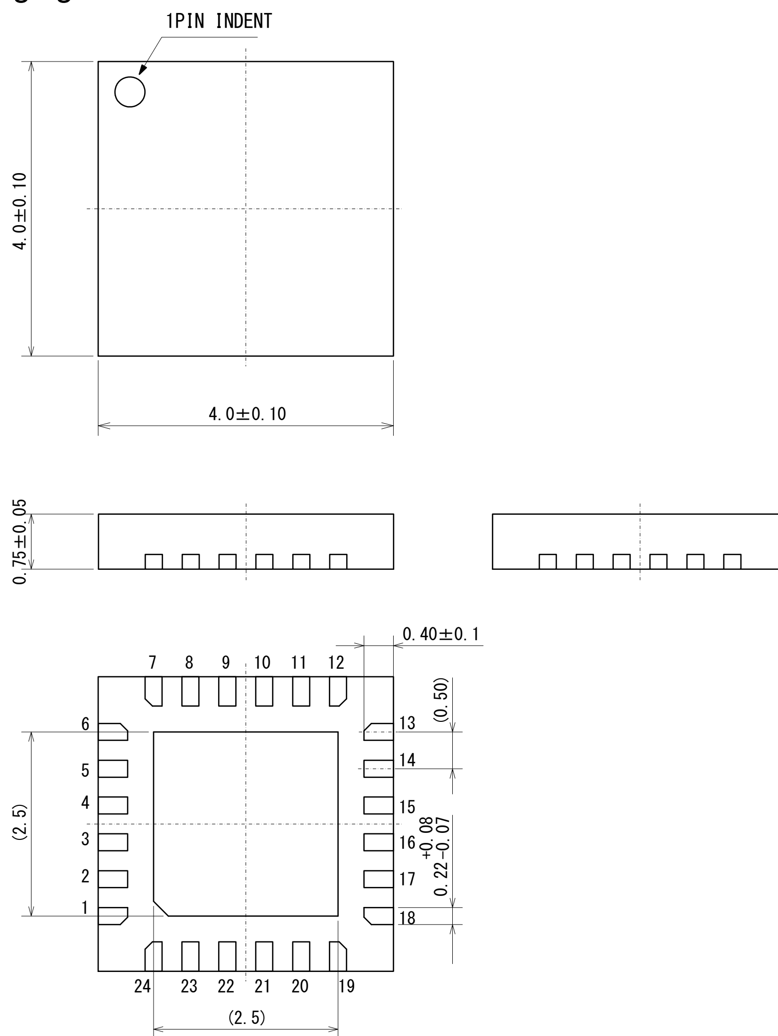
外形寸法図 Packaging Information / 参考パターン寸法 Reference Pattern Layout Dimensions

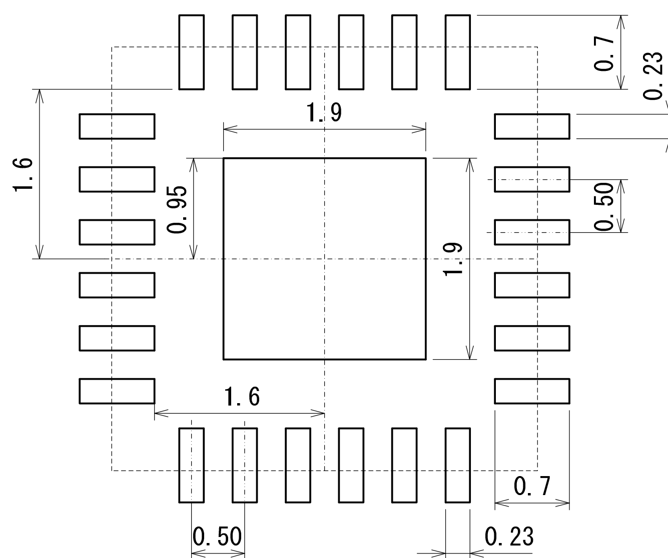
QFN0404-24C

●外形寸法図 / Packaging Information

Unit: (mm)



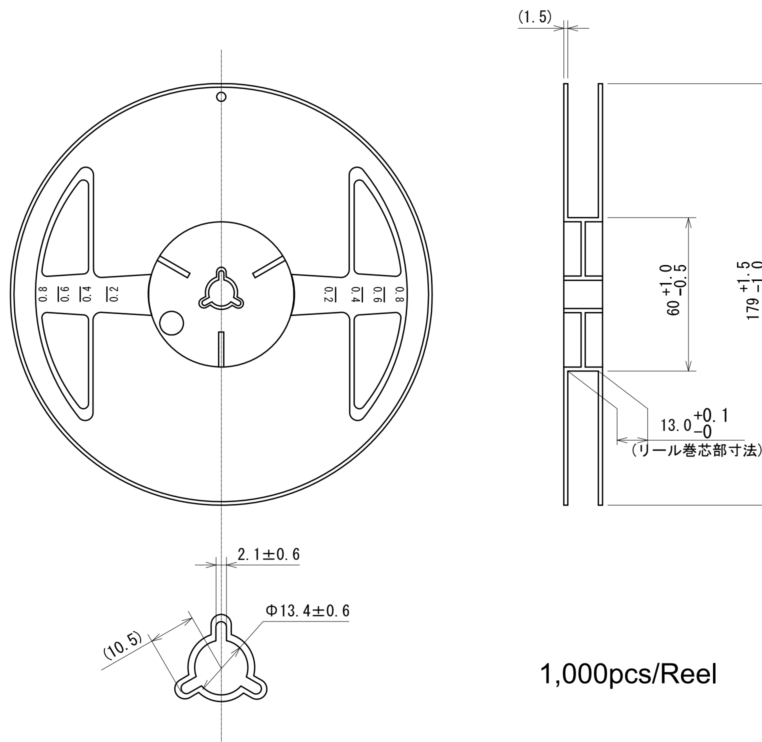
●参考パターンレイアウト/
Reference Pattern Layout



テーピング仕様 / Taping Specifications

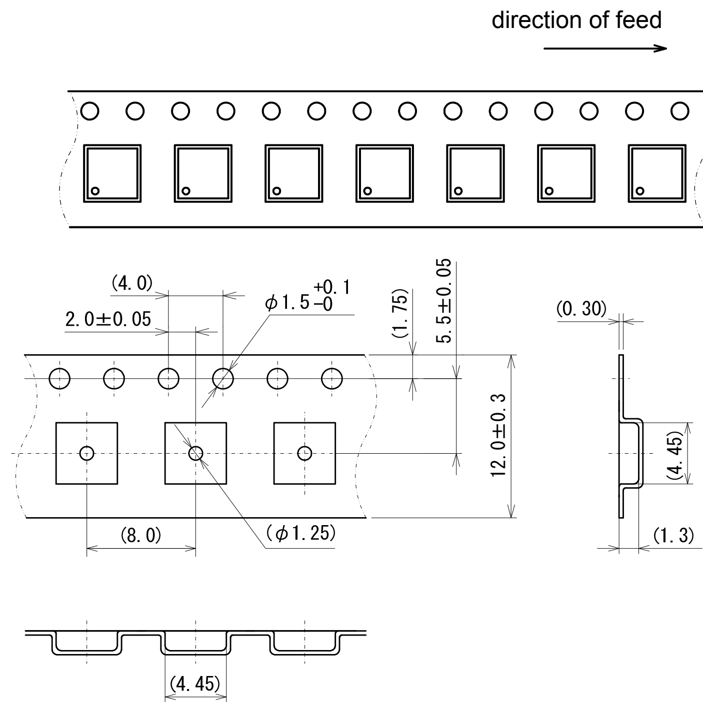
QFN0404-24C

●リール/Reel



1,000pcs/Reel

●テーピング仕様/Taping Specifications



R Type :[Device orientation : Right]

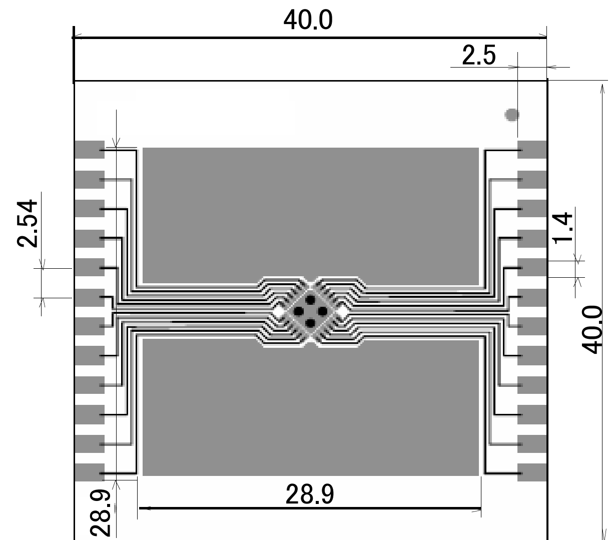
Standard feed

QFN0404-24C Power Dissipation

Power dissipation data for the QFN0404-24C is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as the reference data taken in the following condition.

1. Measurement Condition

Condition: Mount on a board
Ambient: Natural convection
Soldering: Lead (Pb) free
Board Dimensions: 40 x 40 mm ($1600mm^2$)
Board Structure: 4 Copper Layers
Each layer is 50% connected
to the package heat-sink.
Material: Glass Epoxy (FR-4)
Thickness: 1.0 mm
Through-hole: 4 x 0.4 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Ambient Temperature(℃)	Power Dissipation Pd(mW)	Thermal Resistance(℃/W)
25	1500	66.67
85	600